

ABSTRACT AMENDMENTS

Replace the paragraph at page 47, lines 2-9 with the following paragraph:

A semiconductor package device includes an insulative housing, a semiconductor chip, a terminal and a lead, wherein the insulative housing includes a top surface, a bottom surface, and a peripheral side surface between the top and bottom surfaces, the bottom surface includes a peripheral portion and a central portion within the peripheral portion, the peripheral portion protrudes downwardly from the central portion, the chip includes a conductive pad, and the terminal protrudes downwardly from and extends through the bottom surface and is electrically connected to the pad, the lead protrudes laterally from and extends through the peripheral side surface and is electrically connected to the pad, the terminal and the lead are spaced and separated from one another outside the insulative housing, and the terminal and the lead are electrically connected to one another inside the insulative housing and outside the chip.